CELL

Test Laboratory: COMPTEST/KYOCERA

TCoil_FCC_Cell_SCP-8600_050410

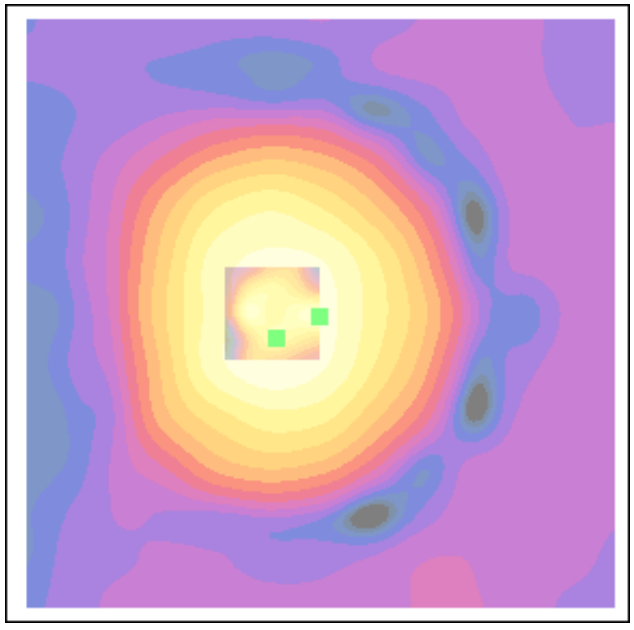
Communication System: CDMA-800, Frequency: 824.7 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/22/2009
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn602,Calibrated: 6/17/2009
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_1013/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
Output Gain: 28.64
BWC applied: 0.143002 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 50.3 dB
ABM1 comp = -2.65 dB A/m
BWC Factor = 0.143002 dB
Location: 3.8, 2.1, 3.7 mm

General Scans_1013/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
Output Gain: 28.64
BWC applied: 0.143002 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 51.5 dB
ABM1 comp = -1.95 dB A/m
BWC Factor = 0.143002 dB
Location: 0.2, 0.2, 3.7 mm



0 dB = 328.2

Test Laboratory: COMPTEST/KYOCERA

TCoil_FCC_Cell_SCP-8600_050410

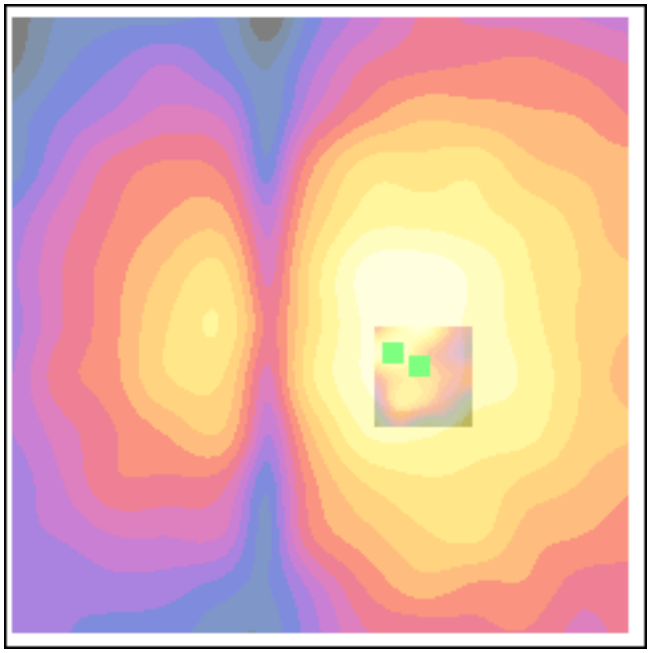
Communication System: CDMA-800, Frequency: 824.7 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/22/2009
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn602,Calibrated: 6/17/2009
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_1013/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
Output Gain: 28.64
BWC applied: 0.143002 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 40.7 dB
ABM1 comp = -11.7 dB A/m
BWC Factor = 0.143002 dB
Location: -7.9, 3.3, 3.7 mm

General Scans_1013/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
Output Gain: 28.64
BWC applied: 0.143002 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 40.7 dB
ABM1 comp = -10.5 dB A/m
BWC Factor = 0.143002 dB
Location: -5.9, 2.2, 3.7 mm



0 dB = 108.1

Test Laboratory: COMPTEST/KYOCERA

TCoil_FCC_Cell_SCP-8600_050410

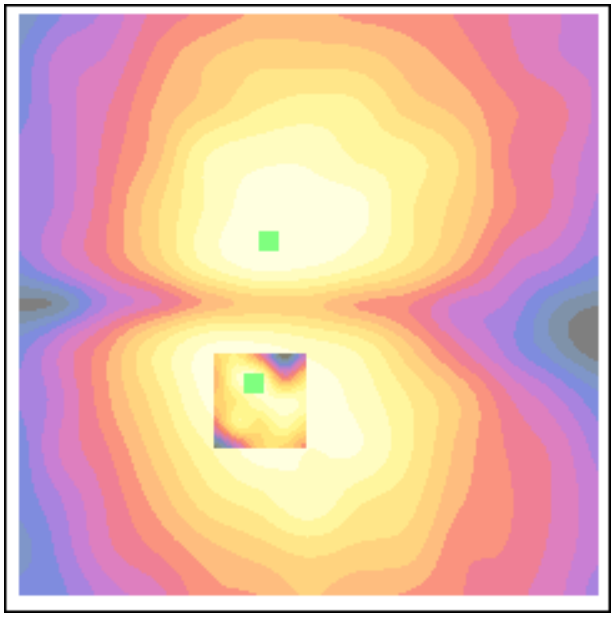
Communication System: CDMA-800, Frequency: 824.7 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/22/2009
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn602,Calibrated: 6/17/2009
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_1013/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
Output Gain: 28.64
BWC applied: 0.143002 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 45.0 dB
ABM1 comp = -10.7 dB A/m
BWC Factor = 0.143002 dB
Location: 3.3, -5.4, 3.7 mm

General Scans_1013/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
Output Gain: 28.64
BWC applied: 0.143002 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 46.8 dB
ABM1 comp = -9.91 dB A/m
BWC Factor = 0.143002 dB
Location: 4.8, 6.7, 3.7 mm



0 dB = 178.7

Test Laboratory: COMPTEST/KYOCERA

TCoil_FCC_Cell_SCP-8600_050410

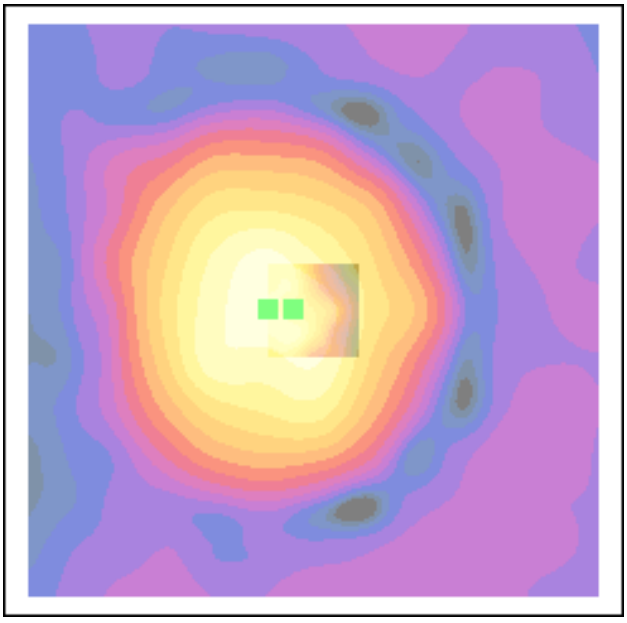
Communication System: CDMA-800, Frequency: 836.49 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/22/2009
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn602,Calibrated: 6/17/2009
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_383/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
Output Gain: 28.64
BWC applied: 0.141977 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 51.8 dB
ABM1 comp = -1.84 dB A/m
BWC Factor = 0.141977 dB
Location: 1.7, 0, 3.7 mm

General Scans_383/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
Output Gain: 28.64
BWC applied: 0.141977 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 50.8 dB
ABM1 comp = -2.89 dB A/m
BWC Factor = 0.141977 dB
Location: 4, 0, 3.7 mm



0 dB = 390.5

Test Laboratory: COMPTEST/KYOCERA

TCoil_FCC_Cell_SCP-8600_050410

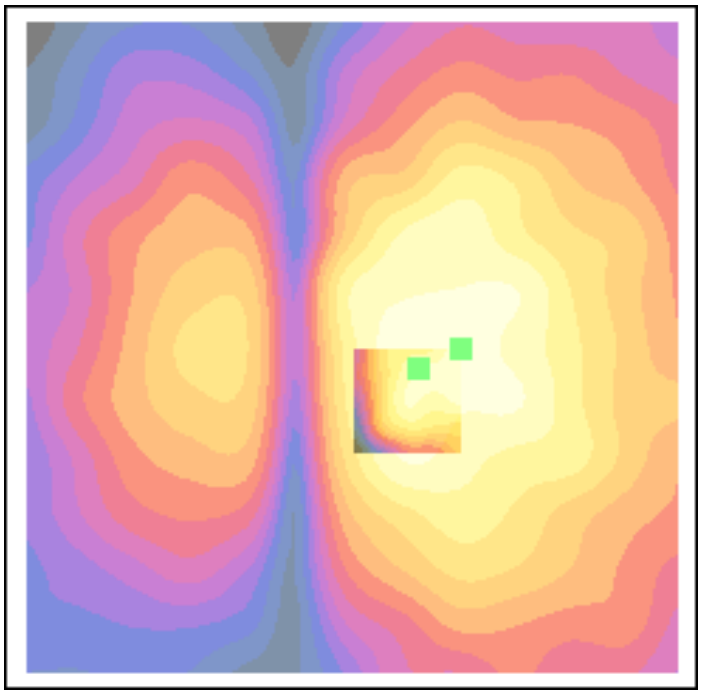
Communication System: CDMA-800, Frequency: 836.49 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/22/2009
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn602,Calibrated: 6/17/2009
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_383/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
Output Gain: 28.64
BWC applied: 0.141977 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 40.3 dB
ABM1 comp = -10.8 dB A/m
BWC Factor = 0.141977 dB
Location: -5, 1.7, 3.7 mm

General Scans_383/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
Output Gain: 28.64
BWC applied: 0.141977 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 40.4 dB
ABM1 comp = -12.3 dB A/m
BWC Factor = 0.141977 dB
Location: -8.2, 0.2, 3.7 mm



0 dB = 103.5

Test Laboratory: COMPTEST/KYOCERA

TCoil_FCC_Cell_SCP-8600_050410

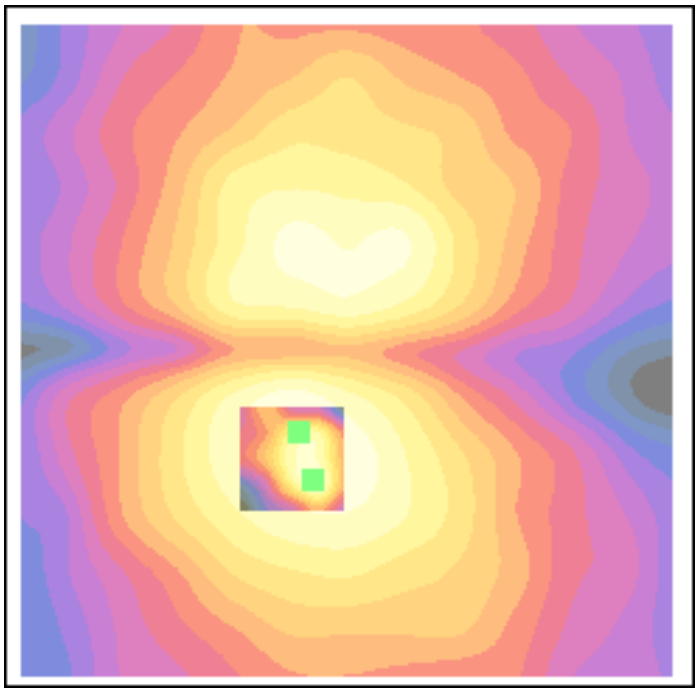
Communication System: CDMA-800, Frequency: 836.49 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/22/2009
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn602,Calibrated: 6/17/2009
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_383/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
Output Gain: 28.64
BWC applied: 0.141977 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 47.6 dB
ABM1 comp = -9.64 dB A/m
BWC Factor = 0.141977 dB
Location: 3.8, 6.2, 3.7 mm

General Scans_383/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
Output Gain: 28.64
BWC applied: 0.141977 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 47.2 dB
ABM1 comp = -9.46 dB A/m
BWC Factor = 0.141977 dB
Location: 2.6, 9.9, 3.7 mm



0 dB = 240.2

Test Laboratory: COMPTEST/KYOCERA

TCoil_FCC_Cell_SCP-8600_050410

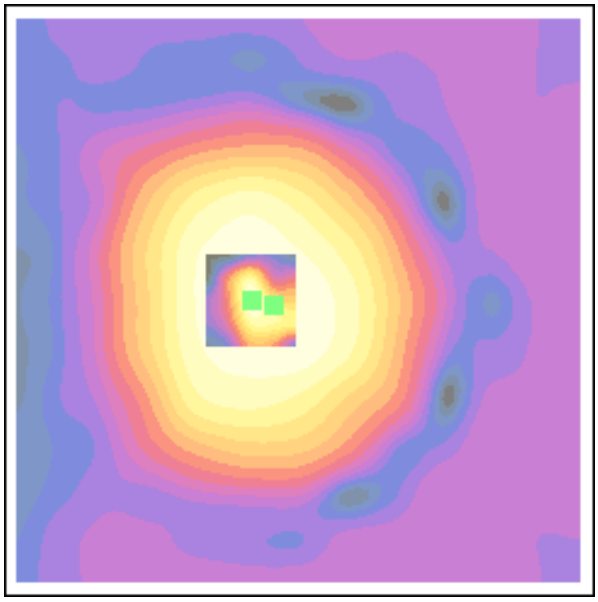
Communication System: CDMA-800, Frequency: 848.31 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/22/2009
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn602,Calibrated: 6/17/2009
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_777/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
Output Gain: 28.64
BWC applied: 0.141977 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 48.8 dB
ABM1 comp = -4.52 dB A/m
BWC Factor = 0.141977 dB
Location: 2.1, 0.4, 3.7 mm

General Scans_777/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
Output Gain: 28.64
BWC applied: 0.141977 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 51.7 dB
ABM1 comp = -1.96 dB A/m
BWC Factor = 0.141977 dB
Location: 4, 0, 3.7 mm



0 dB = 276.8

Test Laboratory: COMPTEST/KYOCERA

TCoil_FCC_Cell_SCP-8600_050410

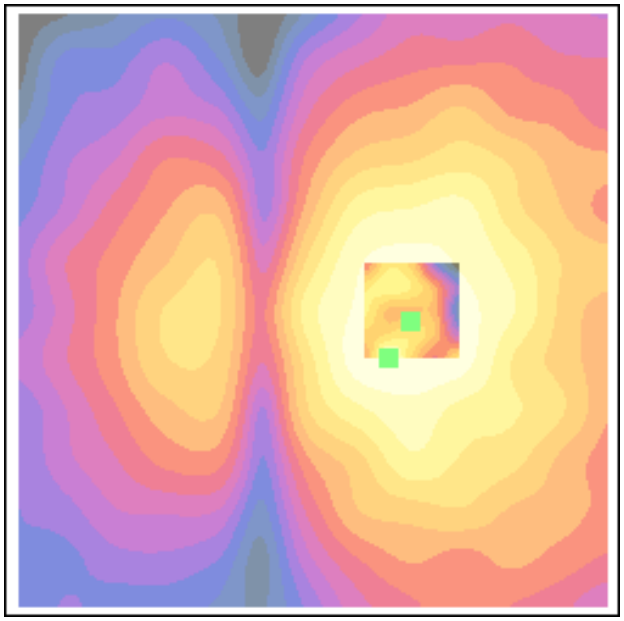
Communication System: CDMA-800, Frequency: 848.31 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/22/2009
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn602,Calibrated: 6/17/2009
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_777/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
Output Gain: 28.64
BWC applied: 0.141977 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 40.6 dB
ABM1 comp = -11.6 dB A/m
BWC Factor = 0.141977 dB
Location: -8.3, 0.8, 3.7 mm

General Scans_777/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
Output Gain: 28.64
BWC applied: 0.141977 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 40.8 dB
ABM1 comp = -10.7 dB A/m
BWC Factor = 0.141977 dB
Location: -6.3, 4, 3.7 mm



0 dB = 107.2

Test Laboratory: COMPTEST/KYOCERA

TCoil_FCC_Cell_SCP-8600_050410

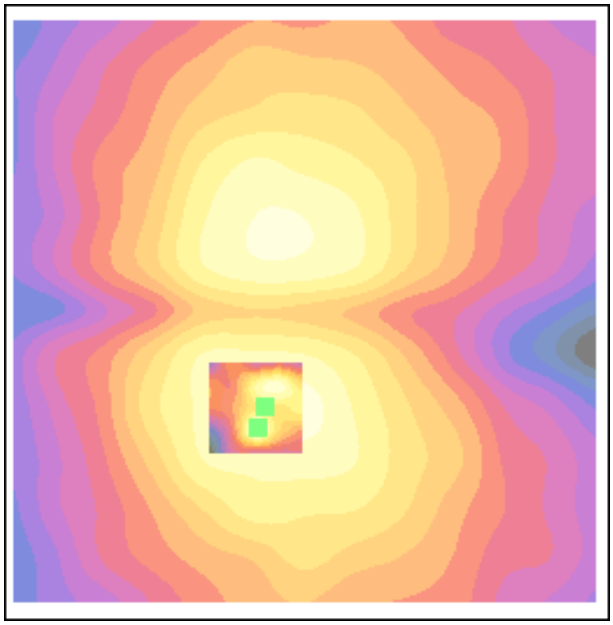
Communication System: CDMA-800, Frequency: 848.31 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/22/2009
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn602,Calibrated: 6/17/2009
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_777/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
Output Gain: 28.64
BWC applied: 0.141977 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 47.8 dB
ABM1 comp = -8.69 dB A/m
BWC Factor = 0.141977 dB
Location: 3.3, 8.3, 3.7 mm

General Scans_777/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
Output Gain: 28.64
BWC applied: 0.141977 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 47.3 dB
ABM1 comp = -8.55 dB A/m
BWC Factor = 0.141977 dB
Location: 4, 10.1, 3.7 mm



0 dB = 246.6

PCS

Test Laboratory: COMPTEST/KYOCERA

TCoil_FCC_PCS_SCP-8600_050310

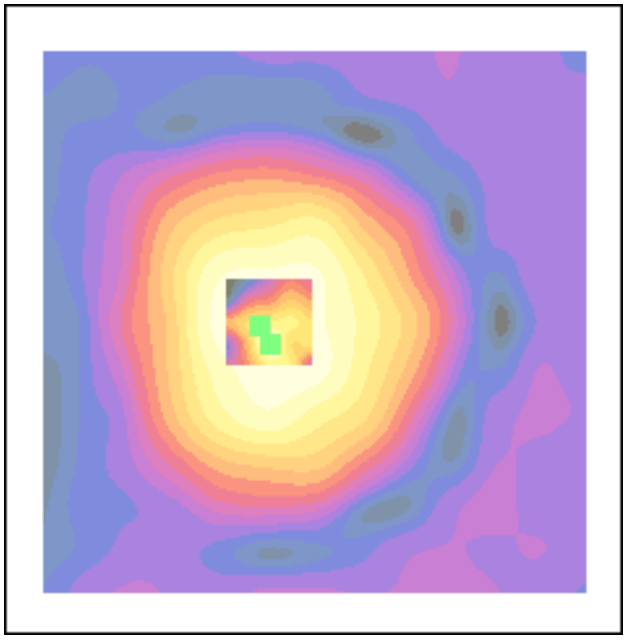
Communication System: CDMA-1900, Frequency: 1851.25 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/22/2009
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn602,Calibrated: 6/17/2009
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_25/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
Output Gain: 28.64
BWC applied: 0.141037 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 49.7 dB
ABM1 comp = -3.83 dB A/m
BWC Factor = 0.141037 dB
Location: 5, 0.4, 3.7 mm

General Scans_25/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
Output Gain: 28.64
BWC applied: 0.141037 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 51.4 dB
ABM1 comp = -2.23 dB A/m
BWC Factor = 0.141037 dB
Location: 4.2, 2, 3.7 mm



0 dB = 304.0

Date: 5/2/2010

Test Laboratory: COMPTEST/KYOCERA

TCoil_FCC_PCS_SCP-8600_050310

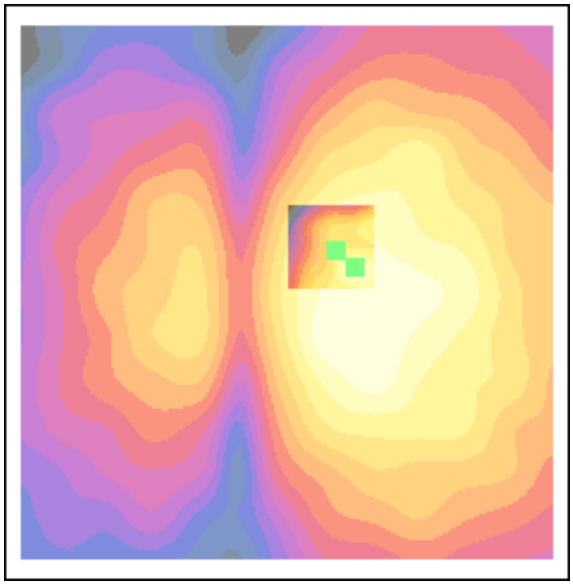
Communication System: CDMA-1900, Frequency: 1851.25 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: $\sigma = 0$ mho/m, $\varepsilon_r = 1$; $\rho = 0$ kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/22/2009
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn602,Calibrated: 6/17/2009
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_25/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
Output Gain: 28.64
BWC applied: 0.141037 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 39.5 dB
ABM1 comp = -11.2 dB A/m
BWC Factor = 0.141037 dB
Location: -4.6, -3.8, 3.7 mm

General Scans_25/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
Output Gain: 28.64
BWC applied: 0.141037 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 40.5 dB
ABM1 comp = -10.8 dB A/m
BWC Factor = 0.141037 dB
Location: -6.4, -2.2, 3.7 mm



0 dB = 94.4

Test Laboratory: COMPTEST/KYOCERA

TCoil_FCC_PCS_SCP-8600_050310

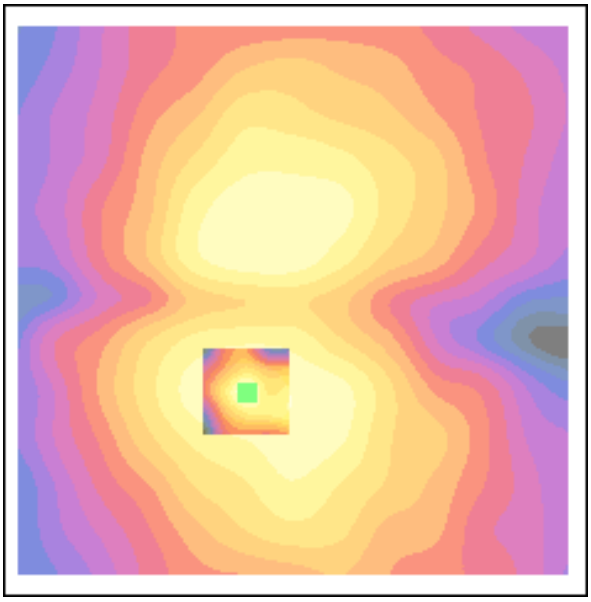
Communication System: CDMA-1900, Frequency: 1851.25 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/22/2009
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn602,Calibrated: 6/17/2009
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_25/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
Output Gain: 28.64
BWC applied: 0.141037 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 47.6 dB
ABM1 comp = -9.23 dB A/m
BWC Factor = 0.141037 dB
Location: 4.2, 8.3, 3.7 mm

General Scans_25/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
Output Gain: 28.64
BWC applied: 0.141037 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 47.0 dB
ABM1 comp = -9.64 dB A/m
BWC Factor = 0.141037 dB
Location: 4.2, 8.3, 3.7 mm



0 dB = 241.2

Test Laboratory: COMPTEST/KYOCERA

TCoil_FCC_PCS_SCP-8600_050310

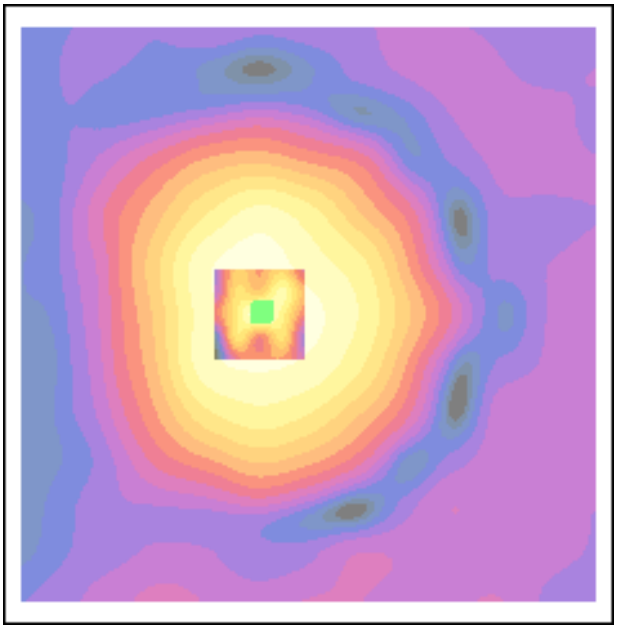
Communication System: CDMA-1900, Frequency: 1880 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/22/2009
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn602,Calibrated: 6/17/2009
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_600/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
Output Gain: 28.64
BWC applied: 0.143002 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 50.8 dB
ABM1 comp = -3.00 dB A/m
BWC Factor = 0.143002 dB
Location: 3.8, -0.4, 3.7 mm

General Scans_600/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
Output Gain: 28.64
BWC applied: 0.143002 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 51.3 dB
ABM1 comp = -2.71 dB A/m
BWC Factor = 0.143002 dB
Location: 4.2, 0, 3.7 mm



0 dB = 348.6

Test Laboratory: COMPTEST/KYOCERA

TCoil_FCC_PCS_SCP-8600_050310

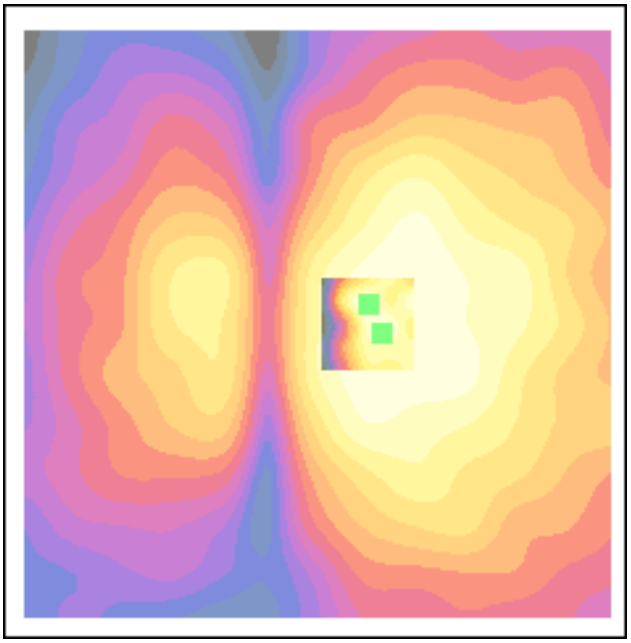
Communication System: CDMA-1900, Frequency: 1880 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/22/2009
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn602,Calibrated: 6/17/2009
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_600/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
Output Gain: 28.64
BWC applied: 0.143002 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 39.4 dB
ABM1 comp = -11.9 dB A/m
BWC Factor = 0.143002 dB
Location: -5.4, 0.8, 3.7 mm

General Scans_600/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
Output Gain: 28.64
BWC applied: 0.143002 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 40.1 dB
ABM1 comp = -10.7 dB A/m
BWC Factor = 0.143002 dB
Location: -4.2, -1.6, 3.7 mm



0 dB = 93.4

Test Laboratory: COMPTEST/KYOCERA

TCoil_FCC_PCS_SCP-8600_050310

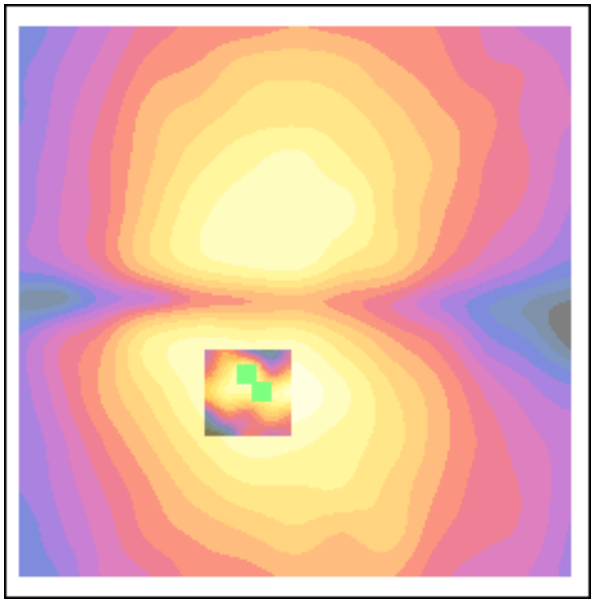
Communication System: CDMA-1900, Frequency: 1880 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/22/2009
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn602,Calibrated: 6/17/2009
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_600/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
Output Gain: 28.64
BWC applied: 0.143002 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 48.0 dB
ABM1 comp = -8.69 dB A/m
BWC Factor = 0.143002 dB
Location: 2.9, 8.3, 3.7 mm

General Scans_600/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
Output Gain: 28.64
BWC applied: 0.143002 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 47.5 dB
ABM1 comp = -9.57 dB A/m
BWC Factor = 0.143002 dB
Location: 4.4, 6.7, 3.7 mm



0 dB = 251.4

Test Laboratory: COMPTEST/KYOCERA

TCoil_FCC_PCS_SCP-8600_050310

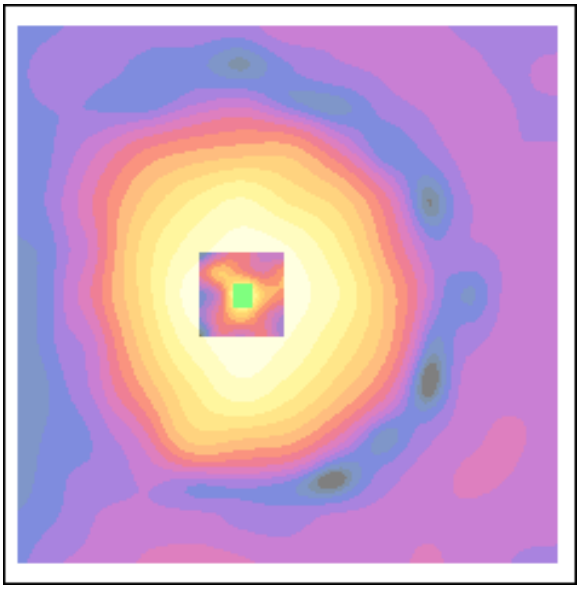
Communication System: CDMA-1900, Frequency: 1908.75 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/22/2009
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn602,Calibrated: 6/17/2009
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_1175/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
Output Gain: 28.64
BWC applied: 0.141977 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 50.0 dB
ABM1 comp = -3.56 dB A/m
BWC Factor = 0.141977 dB
Location: 4.2, 0.4, 3.7 mm

General Scans_1175/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
Output Gain: 28.64
BWC applied: 0.141977 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 52.4 dB
ABM1 comp = -1.35 dB A/m
BWC Factor = 0.141977 dB
Location: 4, 0, 3.7 mm



0 dB = 317.1

Test Laboratory: COMPTEST/KYOCERA

TCoil_FCC_PCS_SCP-8600_050310

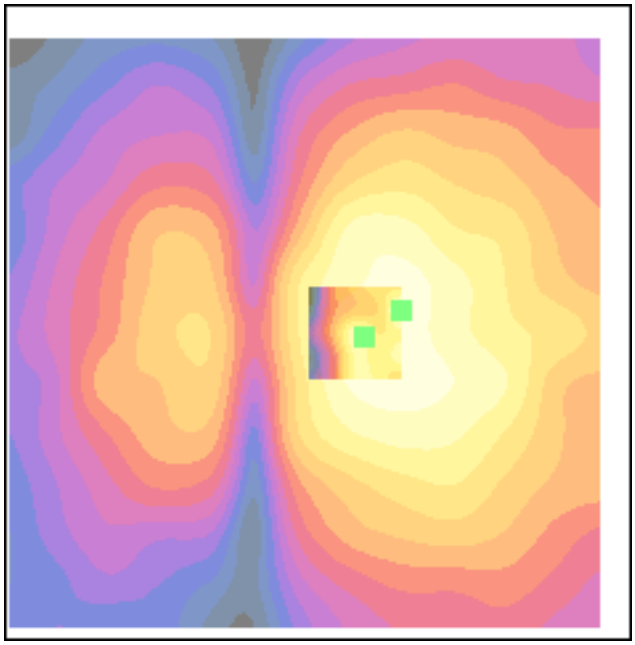
Communication System: CDMA-1900, Frequency: 1908.75 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/22/2009
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn602,Calibrated: 6/17/2009
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_1175/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
Output Gain: 28.64
BWC applied: 0.141977 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 40.6 dB
ABM1 comp = -10.4 dB A/m
BWC Factor = 0.141977 dB
Location: -5, 0.4, 3.7 mm

General Scans_1175/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
Output Gain: 28.64
BWC applied: 0.141977 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 41.0 dB
ABM1 comp = -11.7 dB A/m
BWC Factor = 0.141977 dB
Location: -8.2, -2, 3.7 mm



0 dB = 106.7

Test Laboratory: COMPTEST/KYOCERA

TCoil_FCC_PCS_SCP-8600_050310

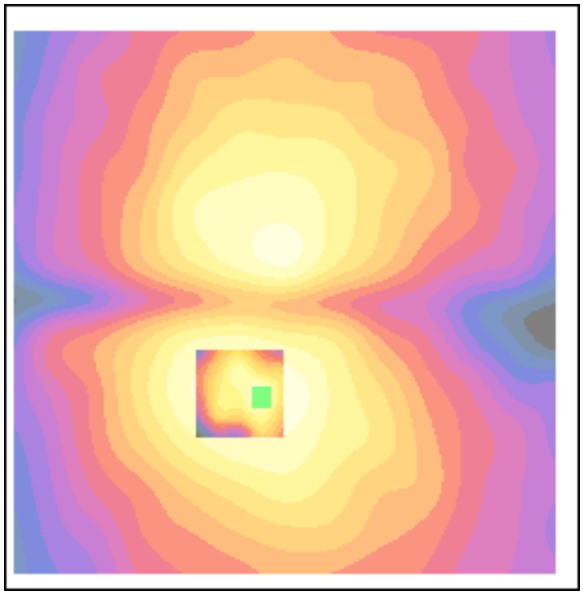
Communication System: CDMA-1900, Frequency: 1908.75 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/22/2009
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn602,Calibrated: 6/17/2009
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_1175/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
Output Gain: 28.64
BWC applied: 0.141977 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 47.9 dB
ABM1 comp = -9.22 dB A/m
BWC Factor = 0.141977 dB
Location: 2.1, 8.7, 3.7 mm

General Scans_1175/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
Output Gain: 28.64
BWC applied: 0.141977 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 47.3 dB
ABM1 comp = -9.79 dB A/m
BWC Factor = 0.141977 dB
Location: 2.2, 8.5, 3.7 mm



0 dB = 249.4